

Supplier Name: **Texas Instruments Inc. (DUNS# 00-732-1904)**
 Contact Info: ti.com/support
 Form/Declaration Type: **Distribute - RoHS and IEC 62474 DB**
 Created on: **05/28/2022**

Details for "AM3894CCYGA120"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
AM3894CCYGA120	SNAGCU	Level-4-245C-72HR	TI PHILIPPINES A/T	CYG 1031	25x25x2.81	7509.1

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Lid							
Copper and Its Alloys	Copper	7440-50-8	5057.91	99	990000	67.356836	673568
Nickel and Its Alloys	Nickel	7440-02-0	49.5573	0.97	9700	0.659961	6600
Other Inorganic Materials	Silicon Dioxide	7631-86-9	1.5327	0.03	300	0.020411	204
Sub-Total			5109	100	1000000	68.037208	680372
Lid Attach Adhesive							
Other Inorganic Materials	Alkanes	68551-17-7	3.349962	1.875	18750	0.044612	446
Other Inorganic Materials	Silica	7631-86-9	0.223331	0.125	1250	0.002974	30
Other Nonferrous Metals and Alloys	Metal Oxide	Trade Secret	75.932482	42.5	425000	1.011203	10112
Other Plastics and Rubber	Silicone	218163-11-2	25.013053	14	140000	0.333102	3331
Precious Metals	Silver	7440-22-4	74.145835	41.5	415000	0.98741	9874
Sub-Total			178.664663	100	1000000	2.3793	23793
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	140.922586	100	1000000	1.876684	18767
Sub-Total			140.922586	100	1000000	1.876684	18767
Solder Ball							
Aluminum and Its Alloys	Aluminum	7429-90-5	0.002561	0.001	10	0.000034	0
Copper and Its Alloys	Copper	7440-50-8	1.280729	0.5	5000	0.017056	171
Other Nonferrous Metals and Alloys	Iron	7440-89-6	0.051229	0.02	200	0.000692	7
Other Nonferrous Metals and Alloys	Antimony	7440-36-0	0.128073	0.05	500	0.001706	17
Other Nonferrous Metals and Alloys	Arsenic	7440-38-2	0.076844	0.03	300	0.001023	10
Other Nonferrous Metals and Alloys	Bismuth	7440-69-9	0.076844	0.03	300	0.001023	10
Other Nonferrous Metals and Alloys	Cadmium	7440-43-9	0.005123	0.002	20	0.000068	1
Other Nonferrous Metals and Alloys	Tin	7440-31-5	246.837373	96.366	963660	3.287165	32872
Precious Metals	Silver	7440-22-4	7.684371	3	30000	0.102334	1023
Zinc and Its Alloys	Zinc	7440-66-6	0.002561	0.001	10	0.000034	0
Sub-Total			256.145708	100	1000000	3.411125	34111
Solder Bump							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	12.141338	97.699998	977000	0.161688	1617
Precious Metals	Silver	7440-22-4	0.285825	2.300002	23000	0.003806	38
Sub-Total			12.427163	100	1000000	0.165494	1655
Substrate							
Ceramics / Glass	Random E-Glass	65997-17-3	329.59656	18.44	184400	4.38928	43893
Copper and Its Alloys	Copper	7440-50-8	926.7669	51.85	518500	12.341874	123419
Other Inorganic Materials	Silica	7631-86-9	161.22348	9.02	90200	2.147034	21470
Other Nonferrous Metals and Alloys	Barium Sulfate	7727-43-7	9.11574	0.51	5100	0.121395	1214
Other Nonferrous Metals and Alloys	Tin	7440-31-5	25.0236	1.4	14000	0.333242	3332
Other Plastics and Rubber	Other Filler	333.52884	18.66	18.66	186600	4.441646	44416
Precious Metals	Silver	7440-22-4	2.14488	0.12	1200	0.028564	286
Sub-Total			1787.4	100	1000000	23.803035	238030
Underfill							
Other Inorganic Materials	Aluminum Nitride	24304-00-5	2.456639	10	100000	0.032715	327
Other Inorganic Materials	Fused Silica	60676-86-0	15.010065	61.1	611000	0.199891	1999
Other Organic Materials	Proprietary Non Halide Flame Retardant	Trade Secret	0.319363	1.3	13000	0.004253	43
Other Plastics and Rubber	Carbon Black	1333-86-4	0.024566	0.099998	1000	0.000327	3
Thermoplastics	Epoxy	85954-11-6	6.755758	27.500002	275000	0.089967	900
Sub-Total			24.566391	100	1000000	0.327154	3272
Total			7509.126511			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.